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PROTECTIVE TAPE APPLYING AND SEPARATING METHODS

ABSTRACT OF THE DISCLOSURE

A protective tape is applied by a tape applying mechanism on a surface of a wafer suction-supported by a chuck table. The protective tape is cut to the shape of the wafer by a cutter unit. This process is repeated a plurality of times to apply protective tape in a plurality of plies to the wafer surface. The protective tapes applied are separated successively, starting with an uppermost tape, by a separating mechanism of a tape separating apparatus.

(Fig. 1)

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